

# 产品技术规格书

## SPECIFICATION

产品型号 PART NO: <b>KH-10025-A81</b>
客户料号 CUSTOMER PART NO:
客户确认 CUSTOMER APPROVED BY:
确认日期 APPROVED DATE:

RoHS Compliant Parts

拟制 Prepared by:	审核 Checked by :	批准 Approved by:
送样日期 Formed On	产品版本 Document Version (V1.1)	

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## 产品规格书版本更改记录

## Version rejigger track record

版本号 Version	更改记录 Rejigger	拟制 Prepared	批准 Approve	日期 Date
V1.0	首次发行	胡景皓	罗昌桅	2022. 10. 14
V1.1	修改第 3 点外型尺寸 L 数值以及调整外型	胡景皓	罗昌桅	2022. 10. 27
备注： 1、更改产品电性能指标时，版本号需更换（V1.0 换为 V2.0、V3.0……）； 2、更改产品测试方法（包括可靠性测试条件），或更改使用条件时，当前版本号加系列（V1.0 换为 V1.1、V1.2……）。				

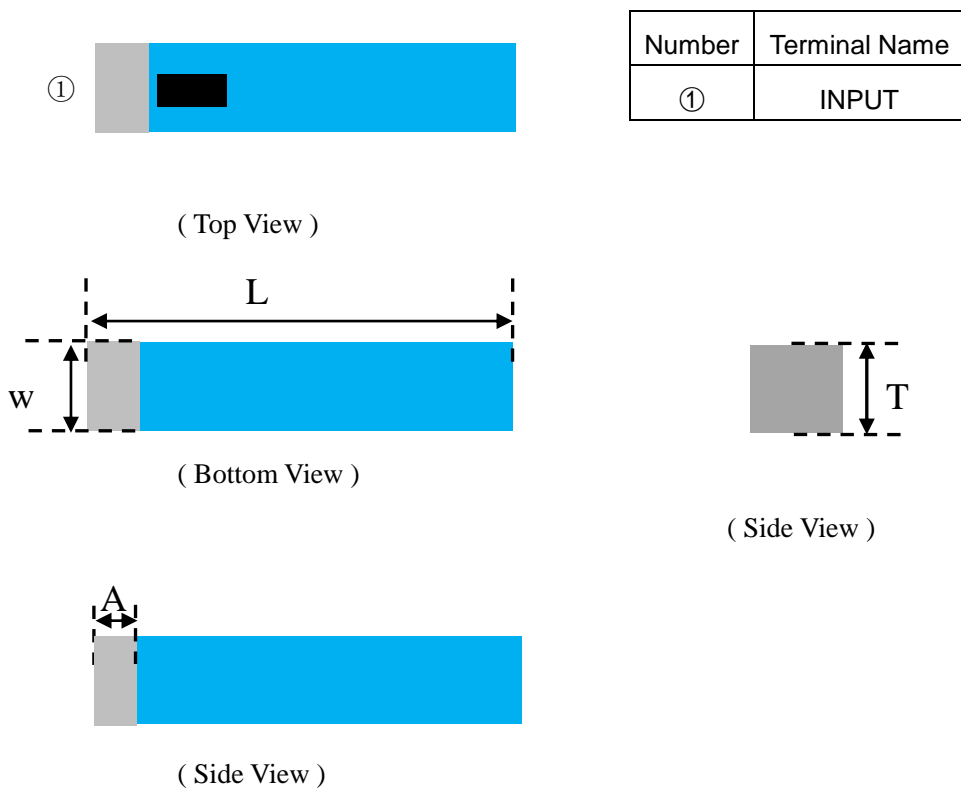
### 1. 概述 INTRODUCTION

"金航标"微波多层陶瓷天线 LA 系列产品设计用于 WLAN、WiFi、蓝牙、PHS，手机多频天线, FM 等小体积 SMD 片式设计。

"KH" Microwave Multi-Layer Ceramic Antenna LA series are designed to be used in WLAN、WiFi、Bluetooth、PHS、 Multiple-band Mobile phone antenna, FM, etc and compact size SMD chip design.

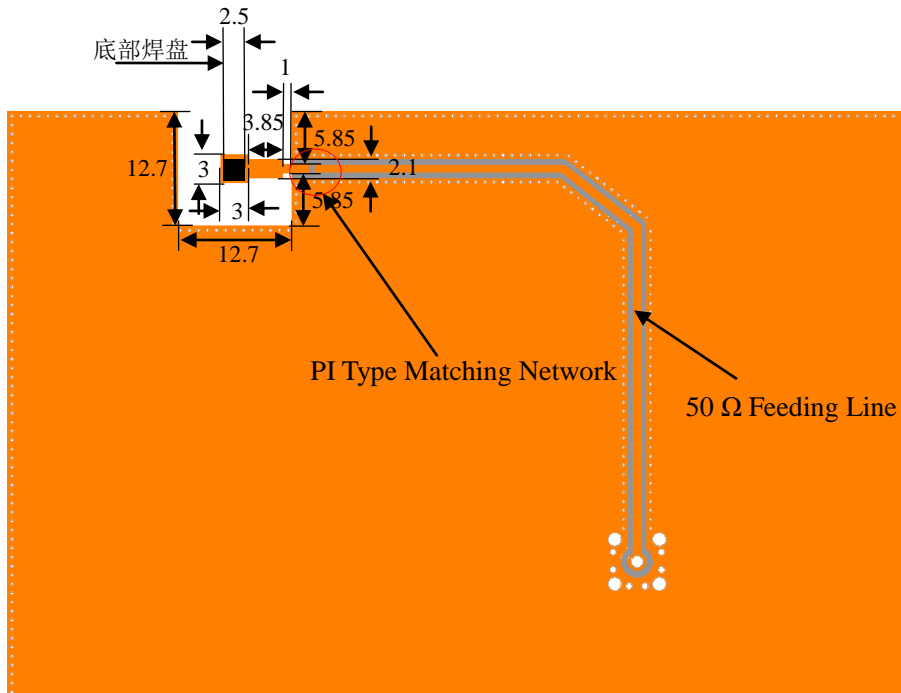
### 2. 型号 KH-10025-A81

### 3. 外型尺寸 Dimensions (Unit: mm)

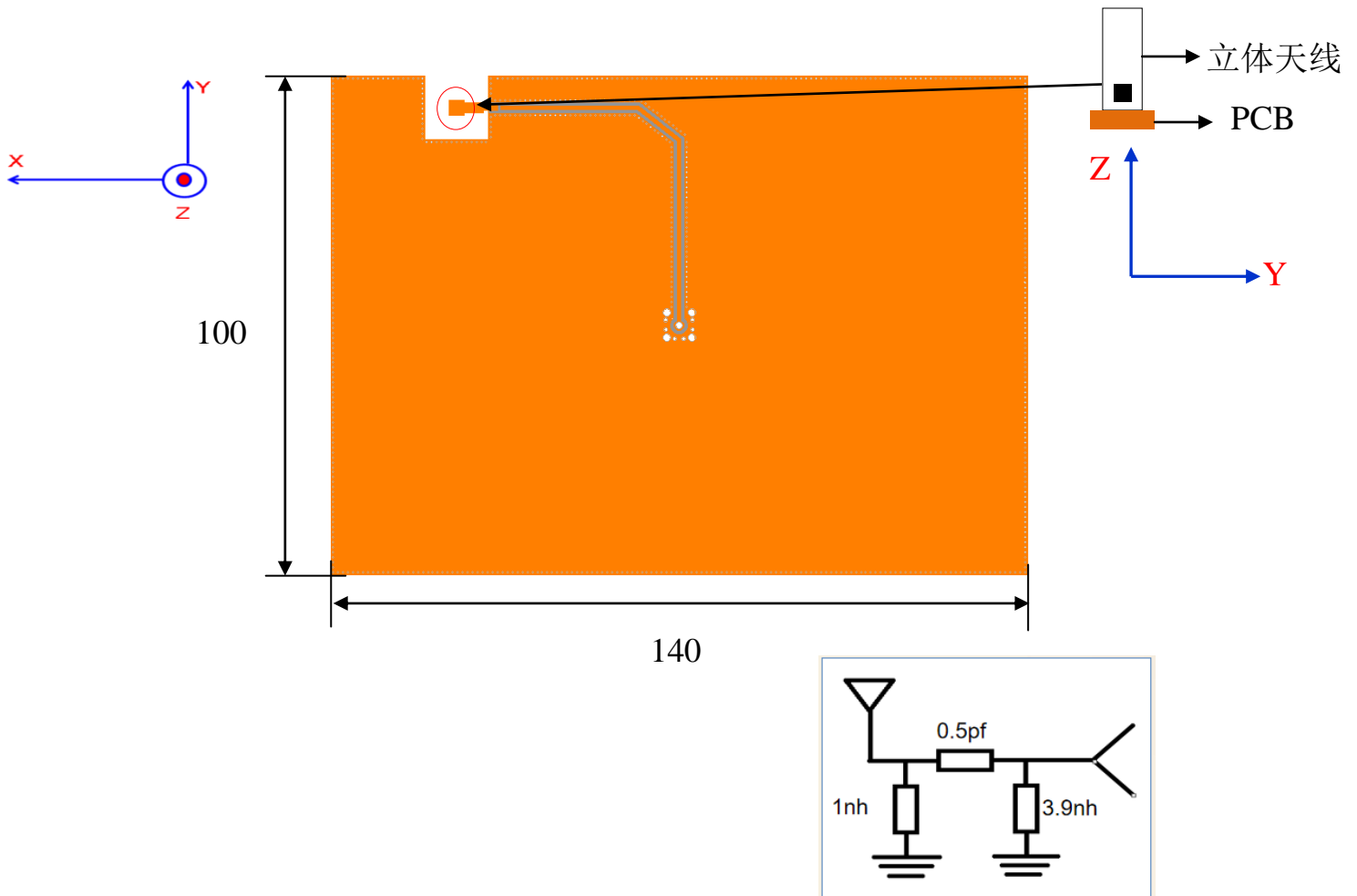


Symbols	L	W	T	A
Dimensions	10+/-0.2	2.5+/-0.2	2.5+/-0.1	0.5+/-0.1

Unit:mm



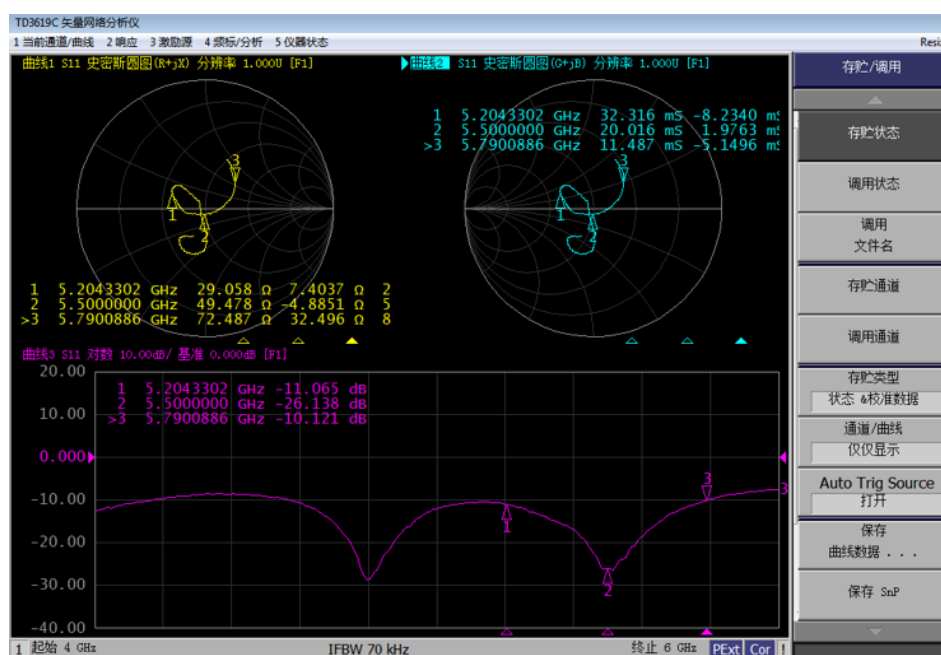
4. 测试电路和匹配电路 Evaluation Board and Matching Circuits



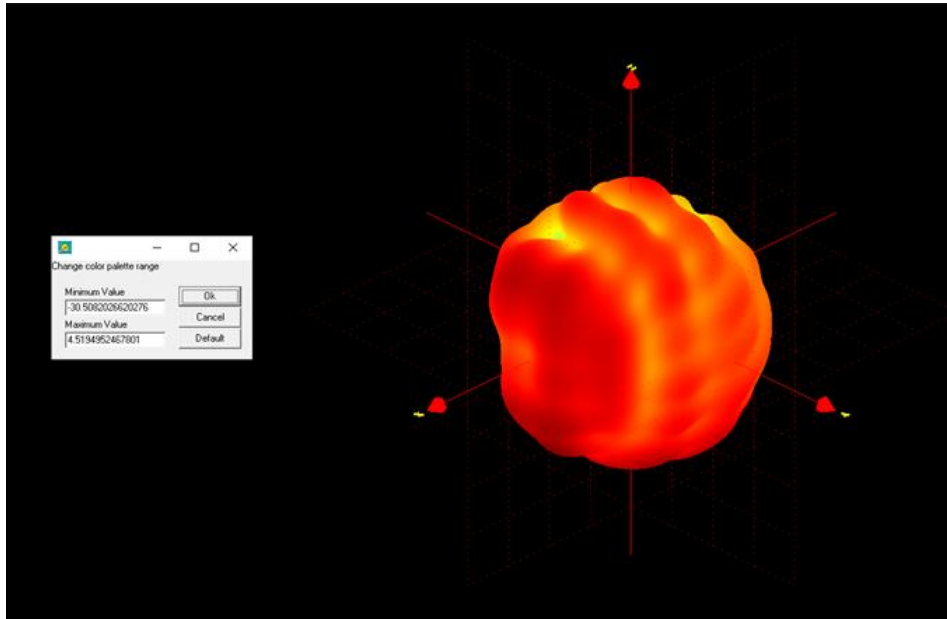
## 5. 电气性能 Electrical Characteristics

No.	Item (项目)	Specifications (特性)
5.1	(带匹配电路测试)After Matching	5500MHz
5.2	Band Width 通带宽度	100MHz Typ.
5.3	Peak Gain 峰值增益	3.2 dBi
5.4	V.S.W.R 驻波比	≤2.0
5.5	Polarization 极化方式	Linear 线性
5.6	Azimuth Beam width 方位角	Omni-directional 全向
5.7	Impedance 阻抗	50 Ω

## 6. 特性曲线 Characteristic curve







Frequency (MHz)	5450	5500	5550
Peak Gain (dBi)	3.1	3.1	3.2
Avg. Gain(dBi)	-3.2	-3.0	-3.1
Efficiency (%)	63	63.3	62

## 8. 可靠性试验 Dependability Test

基准条件：温度范围 Temperature range  $25 \pm 5^{\circ}\text{C}$   
 相对湿度范围 Relative Humidity range 55~75%RH  
 工作温度 Operating Temperature range  $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

### 8.1 耐振动 Vibration Resist

在振动频率为 10~55Hz 振幅为 1.5mm 沿 X.Y.Z 方向各振动 2 小时后测试符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X , Y and Z directions.

## 8.2 耐跌落冲击 Drop Shock

在 100cm 高度处按 X, Y, Z 三个面分别自由跌落在木制地板上共 3 次后测试符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after dropping onto the hard wooden board from the height of 100cm for 3 times each facet of the 3 dimensions of the device.

## 8.3 耐焊接热 Solder Heat Proof

能承受经 120~150°C 的温度预热 120 秒后, 在 255°C+10°C 的焊锡浸 5±0.5 秒, 或 300°C-10°C 的电烙铁焊接 3±0.5 秒, 焊接面无损伤。

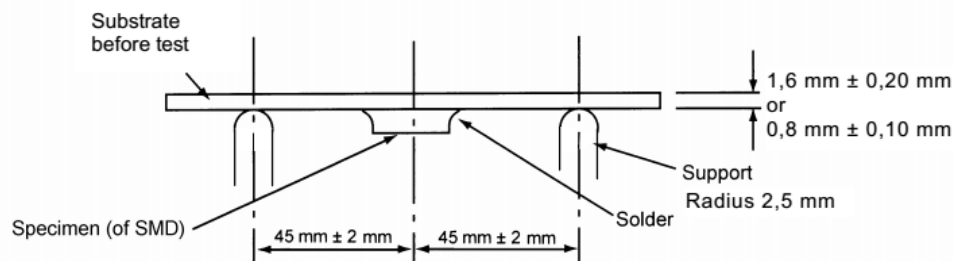
The device should be satisfied after preheating at 120°C~150°C for 120 seconds and dipping in soldering Sn at 255°C+10°C for 5±0.5 seconds, or electric iron 300°C-10°C for 3±0.5 seconds, without damage.

## 8.4 推力试验 Adhesive Strength of Termination

在产品电极端子上或表面上可承受 5N(≤0603); 10N(>0603) 水平推力 10±1 秒而无明显外观损坏与电极移位。

The device have no remarkable damage or removal of the termination after horizontal force of 5N(≤0603); 10N(>0603) with 10±1 seconds.

## 8.5 耐弯曲试验 Bending Resist Test



将产品按图焊在 1.6±0.2mm 或 0.8±0.1mm 的 PCB 板中间, 由箭头方向施力: 1mm/S, 弯曲距离: 1.5mm, 保持 5±1S, 产品金属层无脱落。

Weld the product to the center part of the PCB with the thickness 1.6±0.2mm or 0.8±0.1mm as the illustration shows, and keep exerting force arrow-ward on it at speed of :1mm/S, and hold for 5±1S at the position of 1.5mm bending distance, so far, any peeling off of the product metal coating should not be detected.

## 8.6 耐湿热特性 Moisture Proof

在温度为 60±2°C, 相对湿度 90~95% 的恒温湿箱中放置 96 小时, 在常温中恢复 1~2 小时后测试, 符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature 60±2°C and the relative humidity 90~95% RH for 96 hours and 1~2 hours recovery time under normal condition.

### 8.7 高温特性 High Temperature Endurance

在温度为  $85 \pm 5^\circ\text{C}$  的恒温箱中放置  $96 \pm 2$  小时，在常温中恢复 1~2 小时后测试。符合表 8.1~8.4 规定。

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to temperature  $85 \pm 5^\circ\text{C}$  for  $96 \pm 2$  hours and 1~2 hours recovery time under normal temperature.

### 8.8 低温特性 Low Temperature Endurance

在温度为  $-40^\circ\text{C} \pm 5^\circ\text{C}$  低温箱中放置  $96 \pm 2$  小时后恢复 1~2 小时测试符合表 8.1~8.4 规定。

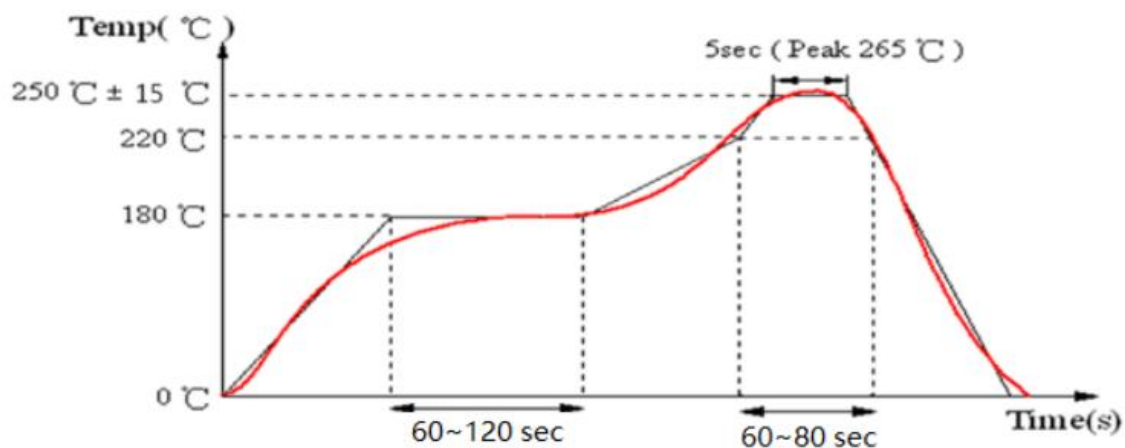
The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature  $-40^\circ\text{C} \pm 5^\circ\text{C}$  for  $96 \pm 2$  hours and to 2 hours recovery time under normal temperature.

### 8.9 温度循环 Temperature Cycle Test

在  $-40^\circ\text{C}$  温度中保持 30 分钟，再在  $+85^\circ\text{C}$  温度中保持 30 分钟，共循环 5 次后在常温中恢复 1~2 小时后测试符合表 8.1~8.4 规定。

The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the low temperature  $-40^\circ\text{C}$  and high temperature  $+85^\circ\text{C}$  for  $30 \pm 2$  min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

## 9. 回流焊温度 Reflow Soldering Standard Condition



## 10. 包装尺寸(1025) Packaging and Dimensions

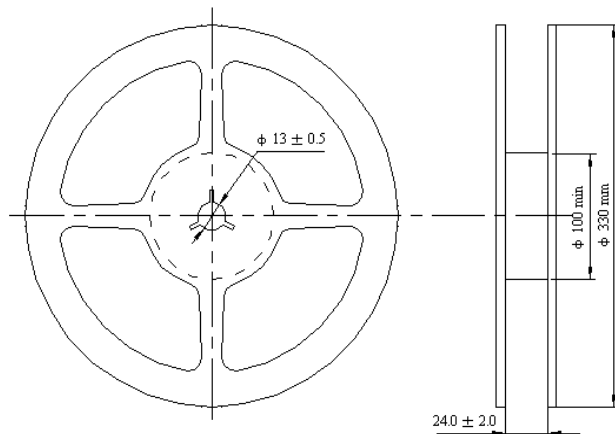
### 10.1 Plastic Tape (待更新)

包装说明: Remarks for Package

载带尾部空穴长度 150~200mm, 载带头部空穴长度 250~300mm, 头部的盖带加长 250mm。

Reserve a length of 150~200mm for the trailer of the carrier and 250~300 mm for the leader of the carrier and further 250mm of cover tape at the leading part of the carrier.

### 10.2 Reel (XX pcs/Reel)



### 10.3 储存条件 Storage Period

产品收到后一年内使用完毕。

Product should be used within twelve months of receipt.

湿敏等级 1 / 储存温度与湿度:

MSL 1 / Storage Temperature Range : <30 degree C, Humidity : <85%RH